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Ordering number : EN8298B

# LC87F5G32A

**CMOSIC** FROM 32K byte, RAM 1024 byte on-chip

# 8-bit 1-chip Microcontroller



http://onsemi.com

#### Overview

The LC87F5G32A is an 8-bit microcomputer that, centered around a CPU running at a minimum bus cycle time of 100ns, integrates on a single chip a number of hardware features such as 32K-byte flash ROM (onboard programmable), 1024-byte RAM, an on-chip debugger, sophisticated 16-bit timers/counters (may be divided into 8bit timers), a 16-bit timer/counter (may be divided into 8-bit timers/counters or 8-bit PWMs), four 8-bit timers with a prescaler, a base timer serving as a time-of-day clock, a high-speed clock counter, a synchronous SIO interface (with automatic block transmission/reception capabilities), an asynchronous/synchronous SIO interface, a UART interface (full duplex), a 12-bit/8-bit 12-channel AD converter, two 12-bit PWM channels, a system clock frequency divider, and a 22-source 10-vector interrupt feature.

#### **Features**

- ■Flash ROM
  - Capable of on-board-programming with wide range, 3.0 to 5.5V, of voltage source.
  - Block-erasable in 128 byte units
  - 32768 × 8-bits (LC87F5G32A)

#### **■**RAM

- 1024 × 9 bits (LC87F5G32A)
- ■Minimum Bus Cycle
  - 100ns (10MHz)

Note: The bus cycle time here refers to the ROM read speed.

- ■Minimum Instruction Cycle Time
  - 300ns (10MHz)

\* This product is licensed from Silicon Storage Technology, Inc. (USA).

#### **■**Ports

• Normal withstand voltage I/O ports

Ports whose I/O direction can be designated in 1-bit units 30 (P1n,P2n,P30 to P36,P70 to P73,PWM0,PWM1,XT2)

Ports whose I/O direction can be designated in 4-bit units 8 (P0n)

Normal withstand voltage input port
 Dedicated oscillator ports
 Reset pins
 1 (XT1)
 2 (CF1, CF2)
 Reset pins

• Power pins 6 (V<sub>SS</sub>1 to 3, V<sub>DD</sub>1 to 3)

#### **■**Timers

• Timer 0: 16-bit timer/counter with a capture register.

Mode 0: 8-bit timer with an 8-bit programmable prescaler (with an 8-bit capture register) × 2-channels

Mode 1: 8-bit timer with an 8-bit programmable prescaler (with an 8-bit capture register) + 8-bit counter (with an 8-bit capture register)

Mode 2: 16-bit timer with an 8-bit programmable prescaler (with a 16-bit capture register)

Mode 3: 16-bit counter (with a 16-bit capture register)

• Timer 1: 16-bit timer/counter that supports PWM/toggle outputs

Mode 0: 8-bit timer with an 8-bit prescaler (with toggle outputs) + with an 8-bit prescaler 8-bit timer/counter (with toggle outputs)

Mode 1: 8-bit PWM with an 8-bit prescaler  $\times$  2-channels

Mode 2: 16-bit timer/counter with an 8-bit prescaler (with toggle outputs)

(toggle outputs also possible from the lower-order 8-bits)

Mode 3: 16-bit timer with an 8-bit prescaler (with toggle outputs) (the lower-order 8-bits can be used as PWM.)

• Timer 4: 8-bit timer with a 6-bit prescaler

• Timer 5: 8-bit timer with a 6-bit prescaler

• Timer 6: 8-bit timer with a 6-bit prescaler (with toggle outputs)

• Timer 7: 8-bit timer with a 6-bit prescaler (with toggle outputs)

• Base timer

1) The clock is selectable from the subclock (32.768kHz crystal oscillation), system clock, and timer 0 prescaler output.

2) Interrupts programmable in 5 different time schemes

#### ■High-speed Clock Counter

- 1) Can count clocks with a maximum clock rate of 20MHz (at a main clock of 10MHz).
- 2) Can generate output real-time.

#### **■**SIO

- SIO0: 8-bit synchronous serial interface
  - 1) LSB first/MSB first mode selectable
  - 2) Built-in 8-bit baudrate generator (maximum transfer clock cycle=4/3 tCYC)
  - 3) Automatic continuous data transmission (1 to 256-bits, specifiable in 1 bit units, suspension and resumption of data transmission possible in 1 byte units)
- SIO1: 8-bit asynchronous/synchronous serial interface

Mode 0: Synchronous 8-bit serial I/O (2- or 3-wire configuration, 2 to 512 tCYC transfer clocks)

Mode 1: Asynchronous serial I/O (half-duplex, 8 data bits, 1 stop bit, 8 to 2048 tCYC baudrates)

Mode 2: Bus mode 1 (start bit, 8 data bits, 2 to 512 tCYC transfer clocks)

Mode 3: Bus mode 2 (start detect, 8 data bits, stop detect)

#### **■**UART

- Full duplex
- 7/8/9 bit data bits selectable
- 1stop bit (2-bit in continuous data transmission)
- Built-in baudrate generator
- ■AD Converter: 12-bits/8-bits × 12-channels
  - 12-bits/8-bits AD converter selectable
  - Automatic reference voltage generation controllable

#### ■PWM: Multifrequency 12-bit PWM × 2-channels

- ■Remote Control Receiver Circuit (sharing pins with P73, INT3, and T0IN)
  - Noise rejection function (noise filter time constant selectable from 1 tCYC, 32 tCYC, and 128 tCYC)
- ■Watchdog Timer
  - External RC watchdog timer
  - Interrupt and reset signals selectable

#### **■**Interrupts

- 22 sources, 10 vector addresses
- 1) Provides three levels (low (L), high (H), and highest (X)) of multiplex interrupt control. Any interrupt requests of the level equal to or lower than the current interrupt are not accepted.
- 2) When interrupt requests to two or more vector addresses occur at the same time, the interrupt of the highest level takes precedence over the other interrupts. For interrupts of the same level, the interrupt into the smallest vector address takes precedence.

No.	Vector Address	Level	Interrupt Source
1	00003H	X or L	INT0
2	0000BH	X or L	INT1
3	00013H	H or L	INT2/T0L/INT4
4	0001BH	H or L	INT3/INT5/base timer
5	00023H	H or L	ТОН
6	0002BH	H or L	T1L/T1H
7	00033H	H or L	SIO0/UART1 receive
8	0003BH	H or L	SIO1/UART1 transmit
9	00043H	H or L	ADC/T6/T7
10	0004BH	H or L	Port 0/T4/T5/PWM0, PWM1

- Priority Levels: X > H > L
- Of interrupts of the same level, the one with the smallest vector address takes precedence.
- ■Subroutine Stack Levels: 512 levels (the stack is allocated in RAM.)
- High-speed Multiplication/Division Instructions

16-bits × 8-bits
24-bits × 16-bits
16-bits ÷ 8-bits
24-bits ÷ 16-bits
(5 tCYC execution time)
(12 tCYC execution time)
(8 tCYC execution time)
(12 tCYC execution time)

#### **■**Oscillation Circuits

• RC oscillation circuit (internal): For system clock

• CF oscillation circuit: For system clock, with internal Rf

• Crystal oscillation circuit: For low-speed system clock, with internal Rf

• Frequency variable RC oscillation circuit (internal): For system clock

#### ■System Clock Divider Function

- Can run on low current.
- The minimum instruction cycle selectable from 300ns, 600ns, 1.2μs, 2.4μs, 4.8μs, 9.6μs, 19.2μs, 38.4μs, and 76.8μs (at a main clock rate of 10MHz).

#### ■Standby Function

- HALT mode: Halts instruction execution while allowing the peripheral circuits to continue operation.
  - 1) Oscillation is not halted automatically.
- 2) Canceled by a system reset or occurrence of an interrupt.
- HOLD mode: Suspends instruction execution and the operation of the peripheral circuits.
- 1) The CF, RC, and crystal oscillators automatically stop operation.
- 2) There are three ways of resetting the HOLD mode.
  - (1) Setting the reset pin to the lower level.
  - (2) Setting at least one of the INT0, INT1, INT2, INT4, and INT5 pins to the specified level.
  - (3) Having an interrupt source established at port 0.
- X'tal HOLD mode: Suspends instruction execution and the operation of the peripheral circuits except the base timer.
- 1) The CF and RC oscillators automatically stop operation.
- 2) The state of crystal oscillation established when the X'tal HOLD mode is entered is retained.
- 3) There are four ways of resetting the X'tal HOLD mode.
  - (1) Setting the reset pin to the low level.
  - (2) Setting at least one of the INT0, INT1, INT2, INT4, and INT5 pins to the specified level.
  - (3) Having an interrupt source established at port.
  - (4) Having an interrupt source established in the base timer circuit.

#### ■Onchip Debugger

• Supports software debugging with the IC mounted on the target board.

#### ■Package Form

• QIP48E(14×14): "Lead-free type" • SQFP48(7×7): "Lead-free type"

#### ■Development Tools

• Evaluation chip: LC87EV690

• Emulator: EVA62S + ECB876600D + SUB875G00 + POD48QFP

ICE-B877300 + SUB875G00 + POD48QFP

• Onchip debugger: TCB87 TypeA + LC87F5G32A

TCB87 TypeB + LC87F5G32A

#### ■Flash ROM Programming boards

Package	Programming boards
QIP48E(14×14)	W87F55256Q
SQFP48(7×7)	W87F55256SQ

#### ■Flash ROM programmer

=1 lash KOM programmer					
Maker	Model		Supported version (Note)	Device	
Flash Support Group, Inc.	Single	AF9708/AF9709/ AF9709B	After 02.40		
(Formerly Ando Electric Co., Ltd.)	0	AF9723 (Main body)	After 02.04	LC87F5G32A FAST	
	Gang	AF9833 (Unit)	After 01.84		
Our company SKK (SANYO FWS)		After 1.02C (Install CD)	LC87F5G32A		

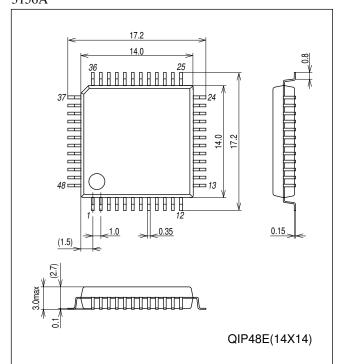
Note: Please check the latest version.

- ■Same package and pin assignment as mask ROM version.
  - 1) LC875G00 series options can be set by using flash ROM data. Thus the board used for mass production can be used for debugging and evaluation without modifications.
  - 2) If the program for the mask ROM version is used, the usable ROM/RAM capacity is the same as the mask ROM version.

#### **Package Dimensions**

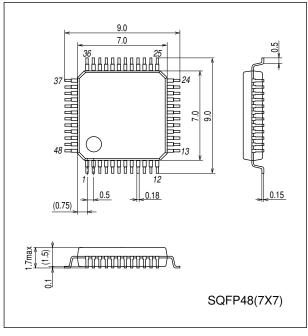
#### unit : mm (tun)

unit : mm (typ) 3156A

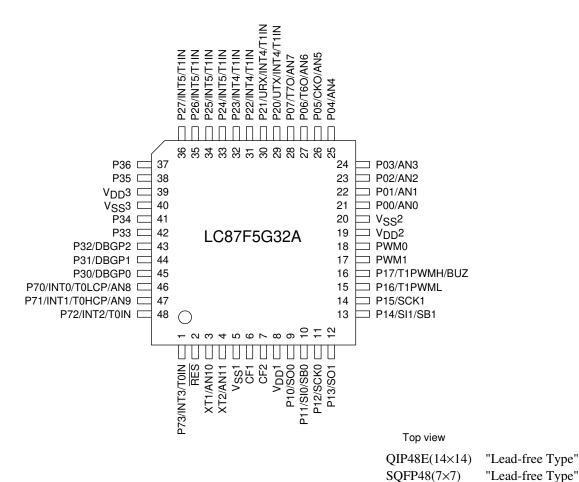


#### **Package Dimensions**

unit : mm (typ) 3163B



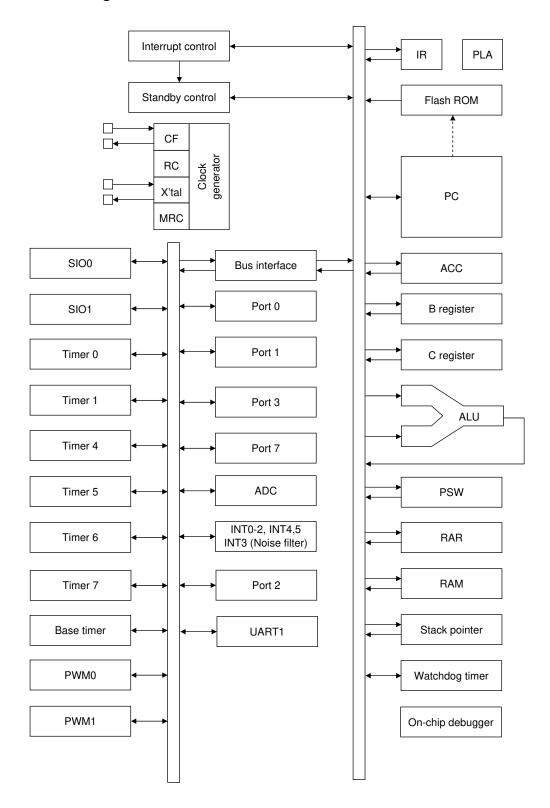
# **Pin Assignment**



SQFP/QIP	NAME
1	P73/INT3/T0IN
2	RES
3	XT1/AN10
4	XT2/AN11
5	V <sub>SS</sub> 1
6	CF1
7	CF2
8	V <sub>DD</sub> 1
9	P10/SO0
10	P11/SI0/SB0
11	P12/SCK0
12	P13/SO1
13	P14/SI1/SB1
14	P15/SCK1
15	P16/T1PWML
16	P17/T1PWMH/BUZ
17	PWM1
18	PWM0
19	V <sub>DD</sub> 2
20	V <sub>SS</sub> 2
21	P00/AN0
22	P01/AN1
23	P02/AN2
24	P03/AN3

SQFP/QIP	NAME
25	P04/AN4
26	P05/CKO/AN5
27	P06/T6O/AN6
28	P07/T7O/AN7
29	P20/UTX/INT4/T1IN
30	P21/URX/INT4/T1IN
31	P22/INT4/T1IN
32	P23/INT4/T1IN
33	P24/INT5/T1IN
34	P25/INT5/T1IN
35	P26/INT5/T1IN
36	P27/INT5/T1IN
37	P36
38	P35
39	V <sub>DD</sub> 3
40	V <sub>SS</sub> 3
41	P34
42	P33
43	P32/DBGP2
44	P31/DBGP1
45	P30/DBGP0
46	P70/INT0/T0LCP/AN8
47	P71/INT1/T0HCP/AN9
48	P72/INT2/T0IN

# **System Block Diagram**



# **Pin Function Chart**

Pin Name	I/O	Description	Option
V <sub>SS</sub> 1 V <sub>SS</sub> 2 V <sub>SS</sub> 3	-	- Power supply pin	Yes
V <sub>DD</sub> 1 V <sub>DD</sub> 2 V <sub>DD</sub> 3	-	+ Power supply pin	No
Port 0	I/O	• 8-bit I/O port	Yes
P00 to P07		I/O specifiable in 4-bit units Pull-up resistors can be turned on and off in 4-bit units HOLD reset input Port 0 interrupt input Shared pins P05: System clock output P06: Timer 6 toggle output P07: Timer 7 toggle output AD converter input port: AN0 (P00) to AN7 (P07)	
Port 1	I/O	8-bit I/O port	Yes
P10 to P17		If I is a specifiable in 1-bit units  I is a specifiable in 1	
Port 2 P20 to P27	I/O	8-bit I/O port     I/O specifiable in 1-bit units     Pull-up resistors can be turned on and off in 1-bit units     Pin functions     P20: UART transmit     P21: UART receive     P20 to P23: INT4 input/HOLD reset input/timer 1 event input/	Yes

Continued on next page.

Continued from preceding page.

Pin Name	I/O			Descr	iption			Option
Port 3	I/O	• 7-bit I/O port						Yes
P30 to P36		• I/O specifiable	in 1-bit units					
		Pull-up resistor	rs can be turned	on and off in 1-bit	units			
		<ul> <li>Shared pins</li> </ul>						
		On-chip debu	gger pins: DBGP0	) to DBGP2 (P30 t	o P32)			
Port 7	I/O	• 4-bit I/O port						No
P70 to P73		I/O specifiable	in 1-bit units					
		Pull-up resistor	rs can be turned	on and off in 1-bit	units			
		<ul> <li>Shared pins</li> </ul>						
	AD converter input port : AN8 (P70), AN9 (P71) P70: INT0 input/HOLD reset input/timer 0L capture input/watchdog timer output							
		P71: INT1 inp	ut/HOLD reset inp	out/timer 0H captu	re input			
		P72: INT2 inp	ut/HOLD reset inp	out/timer 0 event in	nput/timer 0L capt	ure input		
		P73: INT3 inp	ut (with noise filte	r)/timer 0 event in	put/timer 0H captı	ure input		
		Interrupt acknow	wledge type	<del>,</del>	<del>,</del>			
		[ ]	Rising	Falling	Rising &	H level	L level	
			i iisiiig	i aming	Falling	1110401	Licvoi	
		INT0	enable	enable	disable	enable	enable	
		INT1	enable	enable	disable	enable	enable	
		INT2	enable	enable	enable	disable	disable	
		INT3	enable	enable	enable	disable	disable	
PWM0, PWM1	I/O	• PWM0 and P\	VM1 output ports					No
		General-purpo	se I/O available					
RES	Input	Reset pin	·		·			No
XT1	Input	• 32.768kHz cry	stal oscillator inp	ut pin				No
		Shared pins	-	•				
		General-purpo	se input port					
		AD converter	input port: AN10					
		Must be conne	Must be connected to V <sub>DD</sub> 1 if not to be used					
XT2	I/O	• 32.768kHz cry	stal oscillator out	put pin				No
		Shared pins						
		General-purpo	se I/O port					
		AD converter	input port: AN11					
		Must be set for	r oscillation and k	ept open if not to	be used			
CF1	Input	Ceramic resona	ator input pin					No
CF2	Output	Ceramic resona	ator output pin					No

#### **Port Output Types**

The table below lists the types of port outputs and the presence/absence of a pull-up resistor.

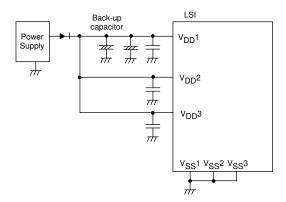
Data can be read into any input port even if it is in the output mode.

Port Name	Option Selected in Units of	Option Type	Output Type	Pull-up Resistor
P00 to P07	1-bit	1	CMOS	Programmable (Note 1)
		2	Nch-open drain	No
P10 to P17	1-bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P20 to P27	1-bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P30 to P36	1-bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P70	-	No	Nch-open drain	Programmable
P71 to P73	-	No	CMOS	Programmable
PWM0, PWM1	-	No	CMOS	No
XT1	-	No	Input for 32.768kHz crystal oscillator (Input only)	No
XT2	-	No	Output for 32.768kHz crystal oscillator (Nch-open drain when in general-purpose output mode)	No

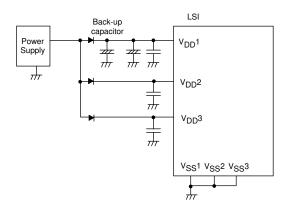
Note 1: Programmable pull-up resistor of Port 0 is specified in nibble units (P00 to P03, P04 to P07).

Note: To reduce V<sub>DD</sub> signal noise and to increase the duration of the backup battery supply, V<sub>SS</sub>1, V<sub>SS</sub>2, and V<sub>SS</sub>3 should connect to each other and they should also be grounded.

Example 1: During backup in hold mode, port output 'H' level is supplied from the back-up capacitor.



Example 2: During backup in hold mode, output is not held high and its value in unsettled.



# **Absolute Maximum Ratings** at Ta = 25 °C, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

	Parameter	Symbol	Pin/Remarks	Conditions			Spe	cification	
		-			V <sub>DD</sub> [V]	min	typ	max	unit
Maximum supply voltage		V <sub>DD</sub> max	V <sub>DD</sub> 1, V <sub>DD</sub> 2, V <sub>DD</sub> 3	V <sub>DD</sub> 1=V <sub>DD</sub> 2=V <sub>DD</sub> 3		-0.3		+6.5	
Inp	out voltage	VI	XT1, CF1			-0.3		V <sub>DD</sub> +0.3	V
	out/output tage	VIO	Ports 0, 1, 2, 3 Port 7, PWM0, PWM1, XT2			-0.3		V <sub>DD</sub> +0.3	•
	Peak output current	IOPH(1)	Ports 0, 1, 2, 3	CMOS output select Per 1 applicable pin		-10			
		IOPH(2)	PWM0, PWM1	CMOS output select Per 1 applicable pin		-20			
		IOPH(3)	Ports P71 to P73	Per 1 applicable pin		-5			
1	Mean output current	IOMH(1)	Ports 0, 1, 2, 3	CMOS output select Per 1 applicable pin		-7.5			
output current	(Note 1-1)	IOMH(2)	PWM0, PWM1	CMOS output select Per 1 applicable pin		-15			
utbn		IOMH(3)	Ports P71 to P73	Per 1 applicable pin		-3			
o le/	Total output	ΣΙΟΑΗ(1)	Ports P71 to P73	Total of all applicable pins		-10			
n le	current	ΣΙΟΑΗ(2)	Port 0	Total of all applicable pins		-25			
High level		ΣΙΟΑΗ(3)	Ports 1, PWM0, PWM1	Total of all applicable pins		-25			
		ΣΙΟΑΗ(4)	Ports 0, 1 PWM0, PWM1	Total of all applicable pins		-45			
		ΣΙΟΑΗ(5)	Ports 2, P35, P36	Total of all applicable pins		-25			
		ΣΙΟΑΗ(6)	Ports P30 to P34	Total of all applicable pins		-25			
		ΣΙΟΑΗ(7)	Ports 2, 3	Total of all applicable pins		-45			
	Peak output current	IOPL(1)	Ports P02 to P07 Ports 1, 2, 3 PWM0, PWM1	Per 1 applicable pin				20	mA
		IOPL(2)	Ports P00, P01	Per 1 applicable pin				30	
rtput current		IOPL(3)	Port 7, XT2	Per 1 applicable pin				10	
ıue	Mean output current (Note 1-1)	IOML(1)	Ports P02 to P07 Ports 1, 2, 3 PWM0, PWM1	Per 1 applicable pin				15	
curr		IOML(2)	Ports P00, P01	Per 1 applicable pin				20	
ıhdı		IOML(3)	Port 7, XT2	Per 1 applicable pin				7.5	
	Total output	ΣIOAL(1)	Port 7, XT2	Total of all applicable pins				15	
row level or	current	ΣIOAL(2)	Port 0	Total of all applicable pins				45	
LOW		ΣIOAL(3)	Ports 1, PWM0, PWM1	Total of all applicable pins				45	
		ΣIOAL(4)	Ports 0, 1 PWM0, PWM1	Total of all applicable pins				80	
		ΣIOAL(5)	Ports 2, P35, P36	Total of all applicable pins				45	
		ΣIOAL(6)	Ports P30 to P34	Total of all applicable pins				45	
		ΣIOAL(7)	Ports 2, 3	Total of all applicable pins				60	
Po	wer dissipation	Pd max	SQFP48(7×7)	Ta= -30 to +70°C				190	_
			QIP48E(14×14)					390	mW
-	erating ambient	Topr				-30		+70	
Sto	orage ambient nperature	Tstg				-55		+125	°C

Note 1-1: The mean output current is a mean value measured over 100ms.

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Allowable Operating Conditions at at  $Ta = -30^{\circ}C$  to  $+70^{\circ}C$ ,  $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$ 

Demonstra	O. washaal	Dia/Damada	O a maliki a ma			Specifi	cation	
Parameter	Symbol	Pin/Remarks	Conditions	V <sub>DD</sub> [V]	min	typ	max	unit
Operating	V <sub>DD</sub> (1)	$V_{DD}1=V_{DD}2=V_{DD}3$	0.294μs ≤ tCYC ≤ 200μs		4.0		5.5	
supply voltage	V <sub>DD</sub> (2)		0.367μs ≤ tCYC ≤ 200μs		3.0		5.5	
(Note 2-1)	V <sub>DD</sub> (3)		0.588μs ≤ tCYC ≤ 200μs		2.5		5.5	
Memory sustaining supply voltage	VHD	V <sub>DD</sub> 1=V <sub>DD</sub> 2=V <sub>DD</sub> 3	RAM and register contents sustained in HOLD mode.		2.0		5.5	
High level input voltage	V <sub>IH</sub> (1)	Ports 1, 2, 3 P71 to P73 P70 port input/ interrupt side PWM0, PWM1		2.5 to 5.5	0.3V <sub>DD</sub> +0.7		V <sub>DD</sub>	
	V <sub>IH</sub> (2)	Port 0		2.5 to 5.5	0.3V <sub>DD</sub> +0.7		$V_{DD}$	
	V <sub>IH</sub> (3)	Port 70 watchdog timer side		2.5 to 5.5	0.9V <sub>DD</sub>		$v_{DD}$	V
	V <sub>IH</sub> (4)	XT1, XT2, CF1, RES		2.5 to 5.5	0.75V <sub>DD</sub>		$v_{DD}$	
Low level input voltage	V <sub>IL</sub> (1)	Ports 1, 2, 3 P71 to P73		4.0 to 5.5	V <sub>SS</sub>		0.1V <sub>DD</sub> +0.4	
		P70 port input/ interrupt side PWM0, PWM1		2.5 to 4.0	V <sub>SS</sub>		0.2V <sub>DD</sub>	
	V <sub>IL</sub> (2)	Port 0		4.0 to 5.5	V <sub>SS</sub>		0.15V <sub>DD</sub> +0.4	
				2.5 to 4.0	$V_{SS}$		0.2V <sub>DD</sub>	
	V <sub>IL</sub> (3)	Port 70 watchdog timer side		2.5 to 5.5	V <sub>SS</sub>		0.8V <sub>DD</sub> -1.0	
	V <sub>IL</sub> (4)	XT1, XT2, CF1, RES		2.5 to 5.5	$V_{SS}$		0.25V <sub>DD</sub>	
Instruction cycle	tCYC			4.0 to 5.5	0.294		200	
time	(Note 2-2)			3.0 to 5.5	0.367		200	μs
(Note 2-1)				2.5 to 5.5	0.588		200	
External system clock frequency	FEXCF	CF1	CF2 pin open     System clock frequency     division ratio=1/1	4.0 to 5.5	0.1		10	
			External system clock     duty=50±5%	2.5 to 5.5	0.1		5	MHz
			CF2 pin open	4.0 to 5.5	0.2		20.4	
			System clock frequency division ratio=1/2	2.5 to 5.5	0.1		10	
Oscillation frequency	FmCF(1)	CF1, CF2	10MHz ceramic oscillation See Fig 1.	4.0 to 5.5		10		
range (Note 2-3)	FmCF(2)	CF1, CF2	8MHz ceramic oscillation See Fig 1.	3.0 to 5.5		8		
	FmCF(3)	CF1, CF2	5MHz ceramic oscillation See Fig 1.	2.5 to 5.5		5		MHz
	FmRC		Internal RC oscillation	2.5 to 5.5	0.3	1.0	2.0	
	FmMRC		Frequency variable RC oscillation	2.5 to 5.5		16		
	FsX'tal	XT1, XT2	32.768kHz crystal oscillation See Fig 2.	2.5 to 5.5		32.768		kHz

Note 2-1: V<sub>DD</sub> must be held greater than or equal to 3.0V in the flash ROM onboard programming mode.

Note 2-3: See Tables 1 and 2 for the oscillation constants.

Note 2-2: Relationship between tCYC and oscillation frequency is 3/FmCF at a division ratio of 1/1 and 6/FmCF at a division ratio of 1/2.

# **Electrical Characteristics** at $Ta = -30^{\circ}C$ to $+70^{\circ}C$ , $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

			7 00	55	00			
Damanatan	Ob. a.l	Dia/Danasak	On a distance			Specific	ation	
Parameter	Symbol	Pin/Remarks	Conditions	V <sub>DD</sub> [V]	min	typ	max	unit
High level input current	I <sub>IH</sub> (1)	Ports 0, 1, 2, 3 Port 7 RES PWM0, PWM1	Output disabled Pull-up resistor off V <sub>IN</sub> =V <sub>DD</sub> (Including output Tr's off leakage current)	2.5 to 5.5			1	
	I <sub>IH</sub> (2)	XT1, XT2	For input port specification VIN=VDD	2.5 to 5.5			1	
	I <sub>IH</sub> (3)	CF1	VIN=V <sub>DD</sub>	2.5 to 5.5			15	^
Low level input current	I <sub>IL</sub> (1)	Ports 0, 1, 2, 3 Port 7 RES PWM0, PWM1	Output disabled Pull-up resistor off VIN=VSS (Including output Tr's off leakage current)	2.5 to 5.5	-1			μА
	I <sub>IL</sub> (2)	XT1, XT2	For input port specification V <sub>IN</sub> =V <sub>SS</sub>	2.5 to 5.5	-1			
	I <sub>IL</sub> (3)	CF1	V <sub>IN</sub> =V <sub>SS</sub>	2.5 to 5.5	-15			
High level output	V <sub>OH</sub> (1)	Ports 0, 1, 2, 3	I <sub>OH</sub> = -1mA	4.5 to 5.5	V <sub>DD</sub> -1			
voltage	V <sub>OH</sub> (2)		I <sub>OH</sub> = -0.1mA	2.5 to 5.5	V <sub>DD</sub> -0.5			
	V <sub>OH</sub> (3)	P71 to P73	I <sub>OH</sub> = -0.4mA	4.5 to 5.5	V <sub>DD</sub> -1			
	V <sub>OH</sub> (4)	PWM0, PWM1, P05(System clock output function	I <sub>OH</sub> = -6mA	4.5 to 5.5	V <sub>DD</sub> -1			
	V <sub>OH</sub> (5)		I <sub>OH</sub> = -1.6mA	4.5 to 5.5	V <sub>DD</sub> -0.4			
	V <sub>OH</sub> (6)	used)	I <sub>OH</sub> = -1mA	2.5 to 5.5	V <sub>DD</sub> -0.4			V
Low level output	V <sub>OL</sub> (1)	Ports 0, 1, 2, 3,	I <sub>OL</sub> =10mA	4.5 to 5.5			1.5	
voltage	V <sub>OL</sub> (2)	PWM0, PWM1,	I <sub>OL</sub> =1.6mA	4.5 to 5.5			0.4	
	V <sub>OL</sub> (3)	XT2	I <sub>OL</sub> =1mA	2.5 to 5.5			0.4	
	V <sub>OL</sub> (4)	P00, P01	I <sub>OL</sub> =30mA	4.5 to 5.5			1.5	
	V <sub>OL</sub> (5)	Port 7	I <sub>OL</sub> =1mA	2.5 to 5.5			0.4	
Pull-up resistance	Rpu(1)	Ports 0, 1, 2, 3 Port 7	V <sub>OH</sub> =0.9V <sub>DD</sub>	4.5 to 5.5	15	35	80	l.O
	Rpu(2)	Ports 0, 1, 2, 3 Port 7	V <sub>OH</sub> =0.9V <sub>DD</sub>	2.5 to 4.5	18	50	150	kΩ
Hysteresis voltage	VHYS	RES Ports 1, 2, 7		2.5 to 5.5		0.1V <sub>DD</sub>		٧
Pin capacitance	СР	All pins	For pins other than that under test: V <sub>IN</sub> =V <sub>SS</sub> f=1MHz Ta=25°C	2.5 to 5.5		10		pF

# Serial Input/Output Characteristics at $Ta = -30^{\circ}C$ to $+70^{\circ}C$ , $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$ 1. SIO0 Serial I/O Characteristics (Note 4-1-1)

		Parameter	Symbol	Pin/Remarks	Conditions			Speci	fication	
	Г	rarameter	Symbol	Pin/Remarks	Conditions	V <sub>DD</sub> [V]	min	typ	max	unit
		Frequency	tSCK(1)	SCK0(P12)	See Fig. 6.		2			
	×	Low level pulse width	tSCKL(1)				1			
	Input clock	High level pulse width	tSCKH(1)			2.5 to 5.5	1			tCYC
clock	ч		tSCKHA(1)		Continuous data transmission/reception mode     See Fig. 6.     (Note 4-1-2)		4			ICTO
Serial clock		Frequency	tSCK(2)	SCK0(P12)	CMOS output selected     See Fig. 6.		4/3			
	ž	Low level pulse width	tSCKL(2)		Coo rigi di		1/2			tSCK
	Output clock	High level pulse width	tSCKH(2)			2.5 to 5.5		1/2		ISCK
	nΟ		tSCKHA(2)		Continuous data     transmission/reception mode     CMOS output selected     See Fig. 6.		tSCKH(2) +2tCYC		tSCKH(2) +(10/3) tCYC	tCYC
input	Da	ta setup time	tsDI(1)	SB0(P11), SI0(P11)	Must be specified with respect to rising edge of SIOCLK.	2.5 to 5.5	0.03			
Serial input	Da	ta hold time	thDI(1)		• See Fig. 6.	2.5 to 5.5	0.03			
	clock	Output delay time	tdD0(1)	SO0(P10), SB0(P11)	Continuous data transmission/reception mode     (Note 4-1-3)	2.5 to 5.5			(1/3)tCYC +0.05	μs
Serial output	Input clock		tdD0(2)		Synchronous 8-bit mode     (Note 4-1-3)	2.5 to 5.5			1tCYC +0.05	
Seria	Output clock		tdD0(3)		(Note 4-1-3)	2.5 to 5.5			(1/3)tCYC +0.05	

- Note 4-1-1: These specifications are theoretical values. Add margin depending on its use.
- Note 4-1-2: To use serial-clock-input in continuous trans/rec mode, a time from SI0RUN being set when serial clock is "H" to the first negative edge of the serial clock must be longer than tSCKHA.
- Note 4-1-3: Must be specified with respect to falling edge of SIOCLK. Must be specified as the time to the beginning of output state change in open drain output mode. See Fig. 6.

## 2. SIO1 Serial I/O Characteristics (Note 4-2-1)

		Dawa	Comple el	Dire/De se estes	O a madition and			Speci	fication	
	ŀ	Parameter	Symbol	Pin/Remarks	Conditions	V <sub>DD</sub> [V]	min	typ	max	unit
	¥	Frequency	tSCK(3)	SCK1(P15)	See Fig. 6.		2			
	Input clock	Low level pulse width	tSCKL(3)			2.5 to 5.5	1			10)/0
Serial clock	п	High level pulse width	tSCKH(3)				1			tCYC
Serial	ock	Frequency	tSCK(4)	SCK1(P15)	CMOS output selected     See Fig. 6.		2			
	Low level tSCKL(4) pulse width		tSCKL(4)			2.5 to 5.5		1/2		tSCK
	ō	High level pulse width	tSCKH(4)					1/2		ISON
Serial input	Da	ta setup time	tsDI(2)	SB1(P14), SI1(P14)	Must be specified with respect to rising edge of SIOCLK.	2.5 to 5.5	0.03			
Serial	Da	ta hold time	thDI(2)		• See Fig. 6.	2.5 to 5.5	0.03			
Serial output	Output delay time		tdD0(4)	SO1(P13), SB1(P14)	Must be specified with respect to falling edge of SIOCLK.     Must be specified as the time to the beginning of output state change in open drain output mode.     See Fig. 6.	2.5 to 5.5			(1/3)tCYC +0.05	μѕ

Note 4-2-1: These specifications are theoretical values. Add margin depending on its use.

# Pulse Input Conditions at Ta = -30°C to +70°C, $V_SS1 = V_SS2 = V_SS3 = 0V$

Davamatav	Cumbal	Pin/Remarks	Conditions		Specification			
Parameter	Symbol	Pin/Remarks	Conditions	V <sub>DD</sub> [V]	min	typ	max	unit
High/low level pulse width			Interrupt source flag can be set.     Event inputs for timer 0 or 1 are enabled.	2.5 to 5.5	1			
	tPIH(2) tPIL(2)	INT3(P73) when noise filter time constant is 1/1	Interrupt source flag can be set.     Event inputs for timer 0 are enabled.	2.5 to 5.5	2			tCYC
	tPIH(3) tPIL(3)	INT3(P73) when noise filter time constant is 1/32	Interrupt source flag can be set.     Event inputs for timer 0 are enabled.	2.5 to 5.5	64			
	tPIH(4) tPIL(4)	INT3(P73) when noise filter time constant is 1/128	Interrupt source flag can be set.     Event inputs for timer 0 are enabled.	2.5 to 5.5	256			
	tPIL(5)	RES	Resetting is enabled.	2.5 to 5.5	200			μs

## **AD** Converter Characteristics at $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

<12-bits AD Converter Mode / Ta= -10°C to +50°C>

Davasatav	O:	Dia/Damada	O and this are			Speci	fication	1	
Parameter	Symbol	Pin/Remarks	Conditions	V <sub>DD</sub> [V]	min	typ	max	unit	
Resolution	N	AN0(P00) to		4.75 to 5.25		12		bit	
Absolute accuracy	ET	AN7(P07)	(Note 6-1)	4.75 to 5.25			T.B.D	LSB	
Conversion time	TCAD	AN8(P70) AN9(P71) AN10(XT1)	See conversion time calculation formulas. (Note 6-2)	4.75 to 5.25	38.5		90	μs	
Analog input voltage range	VAIN	AN11(XT2)		4.75 to 5.25	V <sub>SS</sub>		v <sub>DD</sub>	٧	
Analog port input	IAINH		VAIN=V <sub>DD</sub>	4.75 to 5.25			1		
current	IAINL		VAIN=V <sub>SS</sub>	4.75 to 5.25	-1			μΑ	

#### <8-bits AD Converter Mode / Ta= -30°C to +70°C>

Damanatan	0	Dia /Danasalas	O a mediation as			Specif	ication	
Parameter	Symbol	Pin/Remarks	Conditions	V <sub>DD</sub> [V]	min	typ	max	unit
Resolution	Ν	AN0(P00) to		3.0 to 5.5		8		bit
Absolute accuracy	ET	AN7(P07)	(Note 6-1)	3.0 to 5.5			±1.5	LSB
Conversion time	TCAD	AN8(P70) AN9(P71)	See conversion time calculation	4.5 to 5.5	22.5		90	
		AN10(XT1)	formulas. (Note 6-2)	3.0 to 5.5	45		90	μs
Analog input voltage range	VAIN	AN11(XT2)		3.0 to 5.5	V <sub>SS</sub>		$V_{DD}$	<b>V</b>
Analog port input	IAINH		VAIN=V <sub>DD</sub>	3.0 to 5.5			1	
current	IAINL		VAIN=V <sub>SS</sub>	3.0 to 5.5	-1			μА

#### Conversion time calculation formulas:

12-bits AD Converter Mode: TCAD (Conversion time) =  $((52/(\text{division ratio}))+2) \times (1/3) \times \text{tCYC}$ 

8-bits AD Converter Mode: TCAD (Conversion time) =  $((32/(\text{division ratio}))+2) \times (1/3) \times \text{tCYC}$ 

Note 6-1: The quantization error  $(\pm 1/2LSB)$  must be excluded from the absolute accuracy. The absolute accuracy must be measured in the microcontroller's state in which no I/O operations occur at the pins adjacent to the analog input channel.

Note 6-2: The conversion time refers to the period from the time an instruction for starting a conversion process till the time the conversion results register(s) are loaded with a complete digital conversion value corresponding to the analog input value.

The conversion time is 2 times the normal-time conversion time when:

- The first AD conversion is performed in the 12-bit AD conversion mode after a system reset.
- The first AD conversion is performed after the AD conversion mode is switched from 8-bit to 12-bit conversion mode.

# 

Parameter Symbol		Pin/	Conditions			Specific	cation	
Farameter	Remarks		V <sub>DD</sub> [V]	min	typ	Max	unit	
Normal mode consumption current (Note 7-1)	IDDOP(1)	V <sub>DD</sub> 1 =V <sub>DD</sub> 2 =V <sub>DD</sub> 3	FmCF=10MHz ceramic oscillation mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 10MHz side Internal RC oscillation stopped Frequency variable RC oscillation stopped 1/1 frequency division ratio	4.0 to 5.5		7.7	20	
	IDDOP(2)		CF1=20MHz external clock FsX'tal=32.768kHz crystal oscillation mode System clock set to CF1 side Internal RC oscillation stopped Frequency variable RC oscillation stopped 1/2 frequency division ratio	4.0 to 5.5		8.7	20	
	IDDOP(3)		FmCF=5MHz ceramic oscillation mode     FsX'tal=32.768kHz crystal oscillation mode     System clock set to 5MHz side	4.5 to 5.5		5.2	12	mA
	IDDOP(4)		Internal RC oscillation stopped     Frequency variable RC oscillation stopped     1/1 frequency division ratio	4.5 to 5.5		3.5	10	
	IDDOP(5)		FmCF=0Hz (oscillation stopped)     FsX'tal=32.768kHz crystal oscillation mode	4.5 to 5.5		0.7	2.9	
	IDDOP(6)		System clock set to internal RC oscillation     Frequency variable RC oscillation stopped     1/2 frequency division ratio	2.5 to 4.5		0.4	2.1	
	IDDOP(7)		FmCF=0Hz (oscillation stopped)     FsX'tal=32.768kHz crystal oscillation mode     Internal RC oscillation stopped	4.5 to 5.5		1.4	5.3	
	IDDOP(8)		System clock set to 1MHz with frequency variable RC oscillation     1/2 frequency division ratio	2.5 to 4.5		0.9	3.9	
	IDDOP(9)		FmCF=0Hz (oscillation stopped)     FsX'tal=32.768kHz crystal oscillation mode     System clock set to 32.768kHz side	4.5 to 5.5		34	90	
	IDDOP(10)		Internal RC oscillation stopped     Frequency variable RC oscillation stopped     1/2 frequency division ratio	2.5 to 4.5		23	70	μА

Note 7-1: The consumption current value includes none of the currents that flow into the output Tr and internal pull-up resistors.

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Continued from preceding page.

Parameter	Symbol	Pin/	Conditions			Specific	cation	I
	,	remarks		V <sub>DD</sub> [V]	min	typ	max	unit
HALT mode consumption current (Note 7-1)	IDDHALT(1)	V <sub>DD</sub> 1 =V <sub>DD</sub> 2 =V <sub>DD</sub> 3	HALT mode     FmCF=10MHz ceramic oscillation mode     FsX'tal=32.768kHz crystal oscillation mode     System clock set to 10MHz side     Internal RC oscillation stopped     Frequency variable RC oscillation stopped     1/1 frequency division ratio	4.0 to 5.5		3.1	6	
	IDDHALT(2)		HALT mode     CF1=20MHz external clock     FsX'tal=32.768kHz crystal oscillation mode     System clock set to CF1 side     Internal RC oscillation stopped     Frequency variable RC oscillation stopped     1/2 frequency division ratio	4.0 to 5.5		4	9	
	IDDHALT(3)		HALT mode     FmCF=5MHz ceramic oscillation mode     FsX'tal=32.768kHz crystal oscillation mode     System clock set to 5MHz side	4.5 to 5.5		1.9	4.1	mA
	IDDHALT(4)		Internal RC oscillation stopped Frequency variable RC oscillation stopped I/1 frequency division ratio	2.5 to 4.5		1.3	3.0	
	IDDHALT(5)		HALT mode     FmCF=0Hz (oscillation stopped)     FsX'tal=32.768kHz crystal oscillation mode	4.5 to 5.5		0.35	1.4	
	IDDHALT(6)		System clock set to internal RC oscillation     Frequency variable RC oscillation stopped     1/2 frequency division ratio	2.5 to 4.5		0.25	0.95	
	IDDHALT(7)		HALT mode FmCF=0Hz (oscillation stopped) FsX'tal=32.768kHz crystal oscillation mode Internal RC oscillation stopped	4.5 to 5.5		1.1	4	
	IDDHALT(8)	System clock set to 1MHz with frequency variable RC oscillation     1/2 frequency division ratio	2.5 to 4.5		0.8	3.0		
	IDDHALT(9)		HALT mode     FmCF=0Hz (oscillation stopped)     FsX'tal=32.768kHz crystal oscillation mode	4.5 to 5.5		20	51	
	IDDHALT(10)		System clock set to 32.768kHz side     Internal RC oscillation stopped     Frequency variable RC oscillation stopped     1/2 frequency division ratio	2.5 to 4.5		18	35	
HOLD mode	IDDHOLD(1)	V <sub>DD</sub> 1	HOLD mode	4.5 to 5.5		0.04	11	μA
consumption current	IDDHOLD(2)		CF1=V <sub>DD</sub> or open     (External clock mode)	2.5 to 4.5		0.01	8	
Timer HOLD mode	IDDHOLD(3)	V <sub>DD</sub> 1	Timer HOLD mode  • CF1=V <sub>DD</sub> or open	4.5 to 5.5		17	50	
current	IDDHOLD(4)		(External clock mode)  • FsX'tal=32.768kHz crystal oscillation mode	2.5 to 4.5		12	30	

Note 7-1: The consumption current value includes none of the currents that flow into the output Tr and internal pull-up resistors.

# **F-ROM Programming Characteristics** at $Ta = +10^{\circ}C$ to $+55^{\circ}C$ , $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Davasatas	Coursels al	Din/Damarka	O a realistic and		Specification				
Parameter	Symbol	Pin/Remarks	Conditions	V <sub>DD</sub> [V]	min	typ	max	unit	
Onboard programming current	IDDFW	V <sub>DD</sub> 1	128-byte programming     Erasing current included	3.0 to 5.5		25	40	mA	
Programming time	tFW		128-byte programming     Erasing current included     Time for setting up 128-byte data is excluded.	3.0 to 5.5		22.5	45	ms	

# **UART (Full duplex) Operating Conditions** at Ta = -30°C to +70°C, VSS1 = VSS2 = VSS3 = 0V

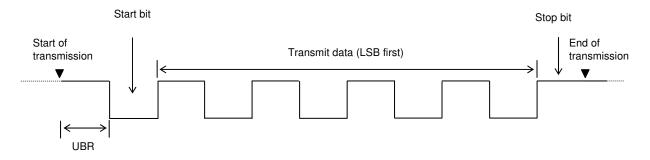
Davasatav	O. mada ad	Pin/Remarks	0		ication			
Parameter	Symbol		Conditions	V <sub>DD</sub> [V]	min	typ	max	unit
Transfer rate	UBR	P20, P21		2.5 to 5.5	16/3		8192/3	tCYC

Data length: 7, 8, and 9 bits (LSB first)

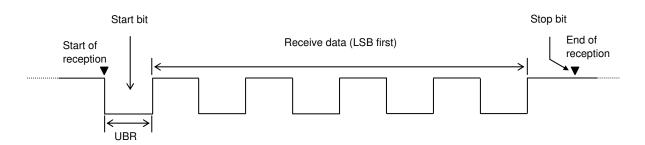
Stop bits: 1-bit (2-bit in continuous data transmission)

Parity bits: Non

#### Example of Continuous 8-bit Data Transmission Mode Processing (first transmit data=55H)



#### Example of Continuous 8-bit Data Reception Mode Processing (first receive data=55H)



#### Characteristics of a Sample Main System Clock Oscillation Circuit

Given below are the characteristics of a sample main system clock oscillation circuit that are measured using a Our designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Table 1 Characteristics of a Sample Main System Clock Oscillator Circuit with a Ceramic Oscillator

Nominal	Vendor Name	Ossillator Nama	Circuit Constant				Operating Voltage		Stabilization me	Damada
Frequency	vendoi ivame	Oscillator Name	C1 [pF]	C2 [pF]	Rf [Ω]	Rd1 [Ω]	Range [V]	typ [ms]	max [ms]	Remarks
400411	MUDATA	CSTCE10M0G52-R0	(10)	(10)	Open	680	4.0 to 5.5	0.1	0.5	Internal C1, C2
10MHz	MURATA	CSTCE10M0G52-B0	(10)	(10)	Open	680	4.0 to 5.5	0.1	0.5	(SMD type)
OMI I-	MUDATA	CSTCE8M00G52-R0	(10)	(10)	Open	1.0k	3.0 to 5.5	0.1	0.5	Internal C1, C2
8MHz	MURATA	CSTCE8M00G52-B0	(10)	(10)	Open	1.0k	3.0 to 5.5	0.1	0.5	(SMD type)
CMI-	MUDATA	CSTCR5M00G53-R0	(15)	(15)	Open	2.2k	2.5 to 5.5	0.2	0.6	Internal C1, C2
5MHz	MURATA	CSTCR5M00G53-B0	(15)	(15)	Open	2.2k	2.5 to 5.5	0.2	0.6	(SMD type)

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized after V<sub>DD</sub> goes above the operating voltage lower limit (see Figure 4).

It is recommended to insert feedback resister (Rf:1M $\Omega$ ) when power supply voltage is used around 2.5V.

#### Characteristics of a Sample Subsystem Clock Oscillator Circuit

Given below are the characteristics of a sample subsystem clock oscillation circuit that are measured using a Our designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Table 2 Characteristics of a Sample Subsystem Clock Oscillator Circuit with a Crystal Oscillator

Nominal	Variday Nasa	Ossillatan Nama		Circuit (	Constant		Operating Voltage	Oscillation S		Damada
Frequency	Vendor Name	Oscillator Name	C3 [pF]	C4 [pF]	Rf [Ω]	Rd2 [Ω]	Range [V]	typ [s]	max [s]	Remarks
32.768kHz	EPSON TOYOCOM	MC-306	18	18	Open	510k	2.5 to 5.5	1.1	3.0	Applicable CL value=12.5pF

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized after the instruction for starting the subclock oscillation circuit is executed and to the time interval that is required for the oscillation to get stabilized after the HOLD mode is reset (see Figure 4).

Note: The components that are involved in oscillation should be placed as close to the IC and to one another as possible because they are vulnerable to the influences of the circuit pattern.

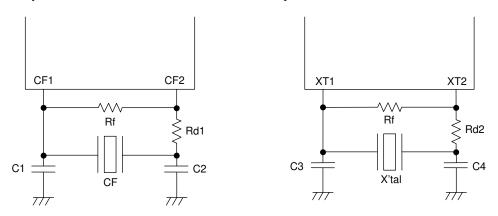


Figure 1 CF Oscillator Circuit

Figure 2 XT Oscillator Circuit

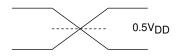
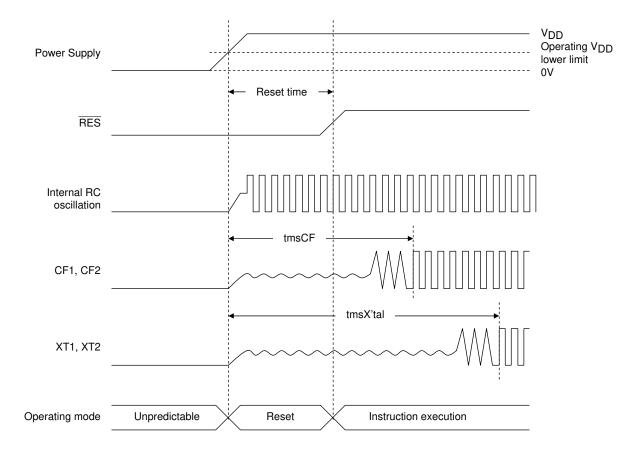
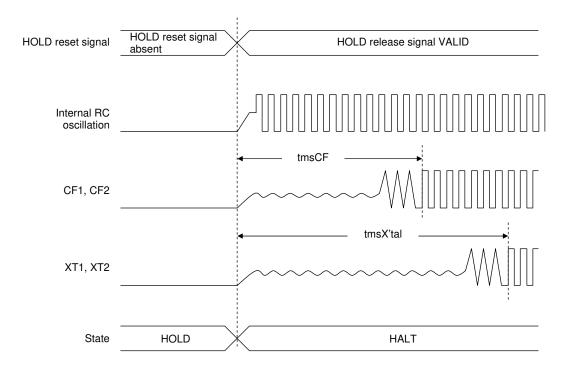


Figure 3 AC Timing Measurement Point

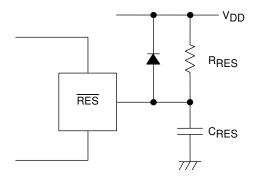


Reset Time and Oscillation Stabilization Time



HOLD Reset Signal and Oscillation Stabilization Time

Figure 4 Oscillation Stabilization Times



#### (Note)

Determine the value of  $C_{RES}$  and  $R_{RES}$  so that the reset signal is present for a period of 200 $\mu$ s after the supply voltage goes beyond the lower limit of the IC's operating voltage.

Figure 5 Reset Circuit

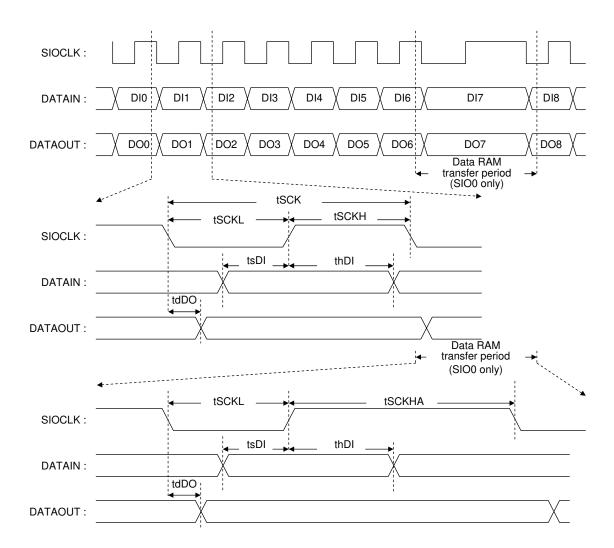


Figure 6 Serial I/O Output Waveforms

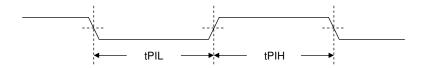


Figure 7 Pulse Input Timing Signal Waveform

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